

### AP9971AGD-VB Datasheet

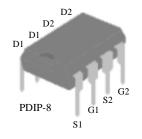
## Dual N-Channel 60 V (D-S) MOSFET

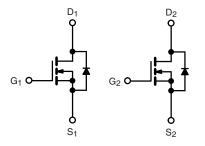
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	60			
$R_{DS(on)} (\Omega)$ at $V_{GS} = 10 V$	0.033			
$R_{DS(on)} (\Omega)$ at $V_{GS} = 4.5 V$	0.045			
I <sub>D</sub> (A) per leg	7			
Configuration	Dual			

#### FEATURES

- TrenchFET® power MOSFET
- 100 % R<sub>g</sub> and UIS tested







N-Channel MOSFET N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V <sub>DS</sub>	60	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current	T <sub>C</sub> = 25 °C	I	7		
	T <sub>C</sub> = 125 °C	I <sub>D</sub>	4		
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	3.6	А	
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	28		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	18		
Single Pulse Avalanche Energy		E <sub>AS</sub>	16.2	mJ	
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	PD	4	W	
	T <sub>C</sub> = 125 °C	гD	1.3	٧V	
Operating Junction and Storage Temperature R	ange	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount <sup>c</sup>	R <sub>thJA</sub>	110	°C/W	
Junction-to-Foot (Drain)		R <sub>thJF</sub>	34	0/10	

#### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- c. When mounted on 1" square PCB (FR4 material).

<b>SPECIFICATIONS</b> ( $T_c = 25$ °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$		60	-	-	v
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$		2.0	2.5	
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	$V_{DS}$ = 0 V, $V_{GS}$ = ± 20 V		-	± 100	nA
		$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V	-	-	1	μA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	50	
		$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$	-	-	150	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{GS} = 10 \text{ V}$	$V_{DS} \ge 5 V$	20	-	-	А
		$V_{GS} = 10 \text{ V}$	I <sub>D</sub> = 4.5 A	-	0.033	-	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 10 V$	I <sub>D</sub> = 4.5 A, T <sub>J</sub> = 125 °C	-	0.066	-	Ω
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 4.5 A, T <sub>J</sub> = 175 °C	-	0.081	-	
		$V_{GS} = 4.5 V$	$I_D = 4 A$	-	0.045	-	
Forward Transconductance <sup>f</sup>	9 <sub>fs</sub>	V <sub>DS</sub>	= 15 V, I <sub>D</sub> = 4.5 A	-	15	-	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>		<sub>S</sub> = 0 V V <sub>DS</sub> = 25 V, f = 1 MHz	-	600	750	pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$		-	110	140	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	50	62	
Total Gate Charge <sup>c</sup>	Qg			-	11.7	18	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 30 \text{ V}, \text{ I}_{D} = 5.3 \text{ A}$	-	1.8	2.7	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	2.8	4.2	
Gate Resistance	Rg	f = 1 MHz		1.3	-	6	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>				7	11	
Rise Time <sup>c</sup>	t <sub>r</sub>	$\label{eq:VDD} \begin{array}{l} V_{\text{DD}}=30 \text{ V}, \ R_{\text{L}}=6.8 \ \Omega \\ I_{\text{D}}\cong 4.4 \ \text{A}, \ V_{\text{GEN}}=10 \ \text{V}, \ R_{g}=1 \ \Omega \end{array}$		-	3.3	5	- ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	22.4	33.5	
Fall Time <sup>c</sup>	t <sub>f</sub>			-	2.1	3.2	
Source-Drain Diode Ratings and Characteristics <sup>b</sup>							
Pulsed Current <sup>a</sup>	I <sub>SM</sub>				-	28	А
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 2 A, V <sub>GS</sub> = 0 V		-	0.75	1.1	V

Notes

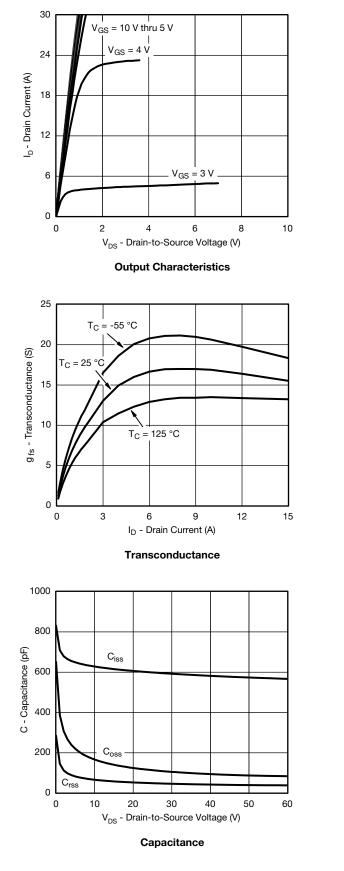
a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.

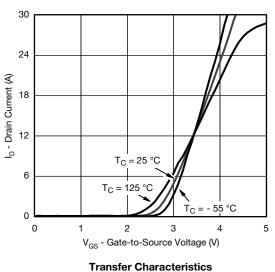
c. Independent of operating temperature.

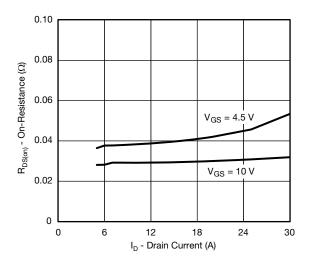
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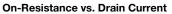


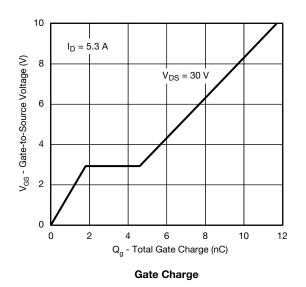
### **TYPICAL CHARACTERISTICS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)





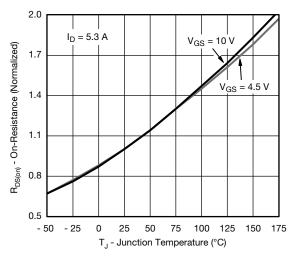




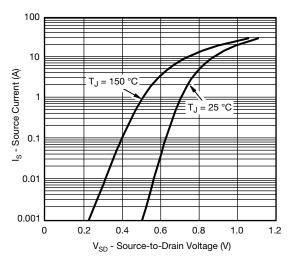




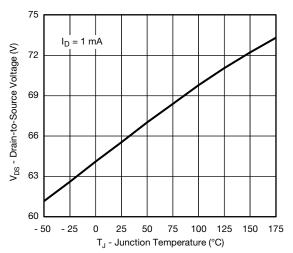
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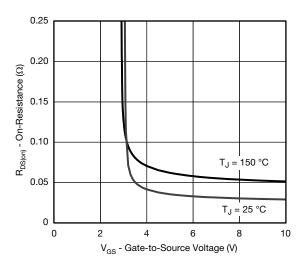
**On-Resistance vs. Junction Temperature** 



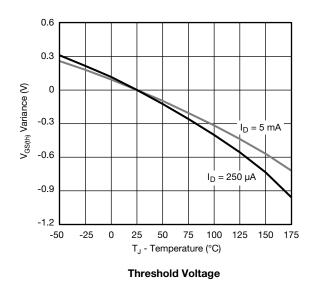
Source Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature

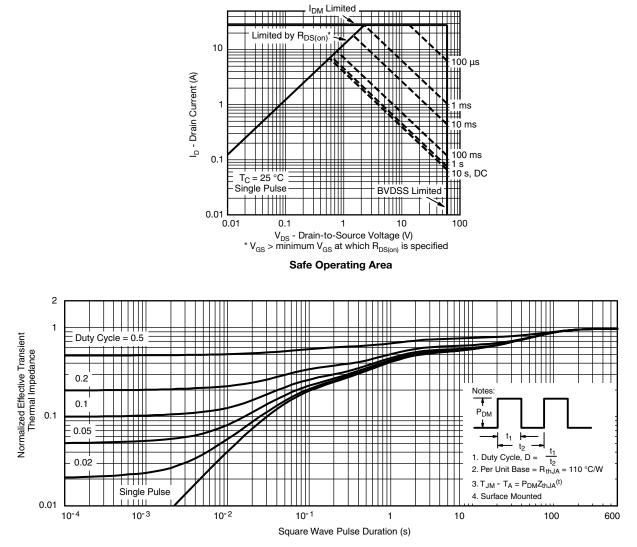


On-Resistance vs. Gate-to-Source Voltage





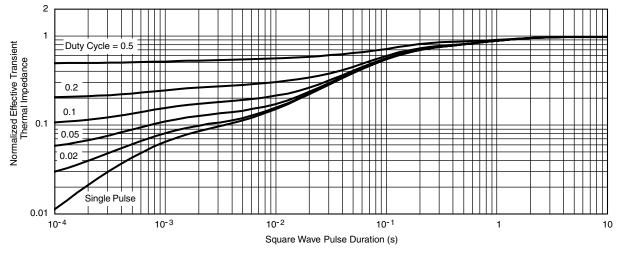
#### **THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



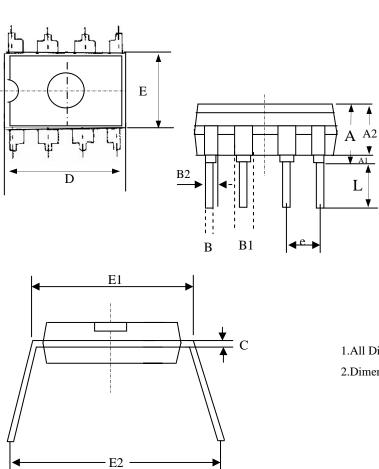
#### **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Foot



# Package Outline : PDIP-8



· · · · · ·				
SYMBOLS	Millimeters			
	MIN	MAX		
Α	3.60	4.50	5.40	
A1	0.38			
A2	2.90	3.95	5.00	
В	0.36	0.46	0.56	
B1	1.10	1.45	1.80	
B2	0.76	0.98	1.20	
С	0.20	0.28	0.36	
D	9.00	9.60	10.20	
Е	6.10	6.65	7.20	
E1	7.62	7.94	8.26	
E2	8.30	9.65	11.00	
e	2.540 BSC			
L	3.18			

All Dimensions Are in Millimeters.
Dimension Does Not Include Mold Protrusions.



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